



## Solderability Test Report for WJ Products With Lead-Free Package Finish

**Package Type:** SOT-89

**Package Finish:** NiPdAu

**Solder:** Lead-Free

### Summary:

10 samples of the WJC lead-free SOT-89 package were subjected to the solderability test in accordance with IPC/EIA/JEDEC J-STD-002B. The temperature of the solder bath was maintained at 260°C, and usage was made of a lead-free solder for this test. The solderability test involved an 8 hour steam aging step to verify the durability of the finish plating.

### Results:

All samples passed the solderability test satisfactorily.

### Test Details:

*Package Type:* SOT-89.

*Terminal Finish:* NiPdAu. (Nickel-Palladium-Gold).

*Solderability Specification:* IPC/EIA/JEDEC J-STD-002B, (equivalent to MIL STD 883, Method 2003).

*Procedure and Evaluation:* Per section 4.2.1 of IPC/EIA/JEDEC J-STD –002B.

*Sample Details:* 10 samples, randomly selected. Total of 30 leads inspected.

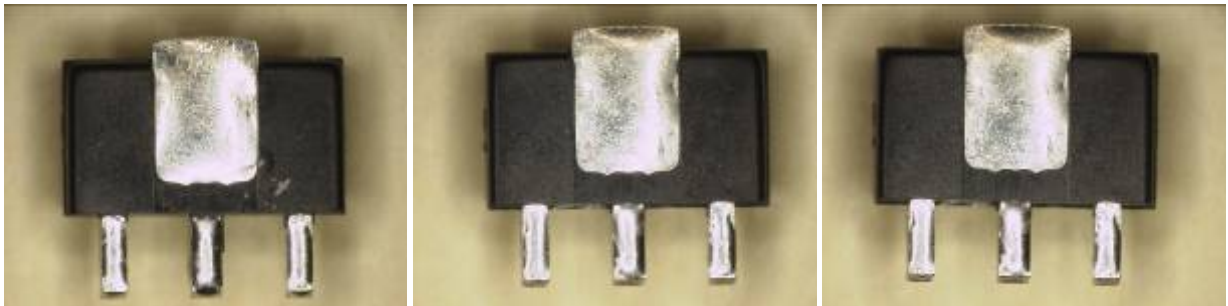
*Lead-Free Solder:* Sn96Ag4.

*Flux Type:* R145.

*Solder Bath Requirements:* 260°C (+5°C, -0°C).

*Coating Durability Test:* 8 hour steam aging, per Category 3, section 1.4 of IPC/EIA/JEDEC J-STD –002B.

**Status:** All samples passed the test. Some sample photos provided below.





**Package Type:** SOT-86

**Package Finish:** Matte Tin

**Solder:** Lead-Free

**Summary:**

10 samples of the WJC lead-free SOT-86 package were subjected to the solderability test in accordance with IPC/EIA/JEDEC J-STD-002B. The temperature of the solder bath was maintained at 260°C, and usage was made of a lead-free solder for this test. The solderability test involved an 8 hour steam aging step to verify the durability of the finish plating.

**Results:**

All samples passed the solderability test satisfactorily.

**Test Details:**

*Package Type:* SOT-86.

*Terminal Finish:* Matte Tin

*Solderability Specification:* IPC/EIA/JEDEC J-STD-002B, (equivalent to MIL STD 883, Method 2003).

*Procedure and Evaluation:* Per section 4.2.1 of IPC/EIA/JEDEC J-STD –002B.

*Sample Details:* 10 samples, randomly selected. Total of 40 leads inspected.

*Lead-Free Solder:* Sn96Ag4.

*Flux Type:* R145.

*Solder Bath Requirements:* 260°C (+5°C, -0°C).

*Coating Durability Test:* 8 hour steam aging, per Category 3, section 1.4 of IPC/EIA/JEDEC J-STD –002B.

**Status:** All samples passed the test. Some sample photos provided below.





**Package Type:** SOT-363

**Package Finish:** Matte Tin

**Solder:** Lead-Free

**Summary:**

10 samples of the WJC lead-free SOT-363 package were subjected to the solderability test in accordance with IPC/EIA/JEDEC J-STD-002B. The temperature of the solder bath was maintained at 260°C, and usage was made of a lead-free solder for this test. The solderability test involved an 8 hour steam aging step to verify the durability of the finish plating.

**Results:**

All samples passed the solderability test satisfactorily.

**Test Details:**

*Package Type:* SOT-363.

*Terminal Finish:* Matte Tin

*Solderability Specification:* IPC/EIA/JEDEC J-STD-002B, (equivalent to MIL STD 883, Method 2003).

*Procedure and Evaluation:* Per section 4.2.1 of IPC/EIA/JEDEC J-STD –002B.

*Sample Details:* 10 samples, randomly selected. Total of 60 leads inspected.

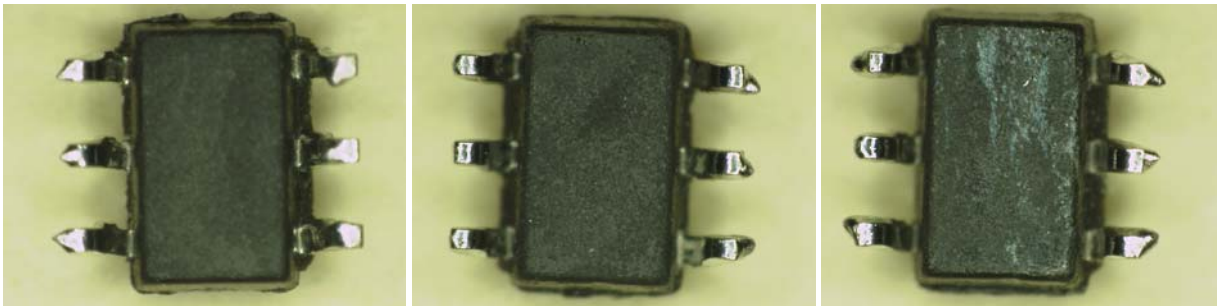
*Lead-Free Solder:* Sn96Ag4.

*Flux Type:* R145.

*Solder Bath Requirements:* 260°C (+5°C, -0°C).

*Coating Durability Test:* 8 hour steam aging, per Category 3, section 1.4 of IPC/EIA/JEDEC J-STD –002B.

**Status:** All samples passed the test. Some sample photos provided below.





## Solderability Test Report for WJ Products With Lead-Free Package Finish

**Package Type:** 28-Pin QFN.

**Package Finish:** Matte Tin

**Solder:** Lead-Free

### Summary:

30 samples of the WJC lead-free QFN package (28-pin) were subjected to the solderability test in accordance with IPC/EIA/JEDEC J-STD-002B. The temperature of the solder bath was maintained at 260°C, and usage was made of a lead-free solder for this test. The solderability test involved an 8 hour steam aging step to verify the durability of the finish plating.

### Results:

All samples passed the solderability test satisfactorily.

### Test Details:

*Package Type:* Quad Flatpack – 28 Pin.

*Terminal Finish:* Matte Tin

*Solderability Specification:* IPC/EIA/JEDEC J-STD-002B, (equivalent to MIL STD 883, Method 2003).

*Procedure and Evaluation:* Per section 4.2.1 of IPC/EIA/JEDEC J-STD –002B.

*Sample Details:* 30 samples, randomly selected, 3 lots. Total of 280 pins inspected per lot.

*Lead-Free Solder:* Sn96Ag4.

*Flux Type:* R145.

*Solder Bath Requirements:* **260C** (+5°C, -0°C).

*Coating Durability Test:* 8 hour steam aging, per Category 3, section 1.4 of IPC/EIA/JEDEC J-STD –002B.

**Status:** All samples passed the test. Some sample photos provided below.

